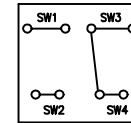
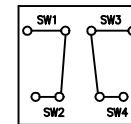


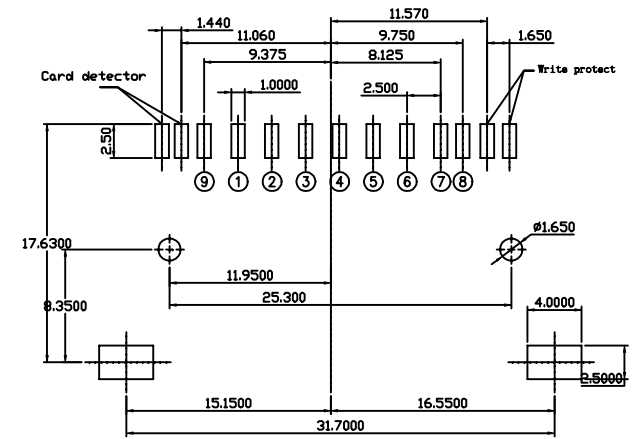
WITHOUT CARD



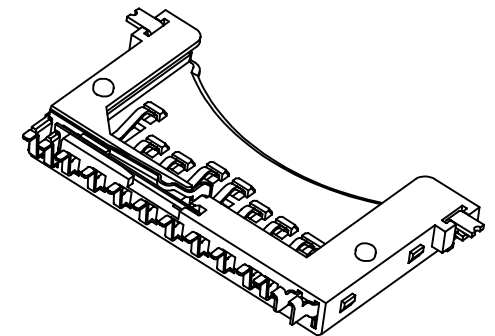
CARD INSERTED
WRITE PROTECT : LOCK



CARD INSERTED
WRITE PROTECT : UNLOCK



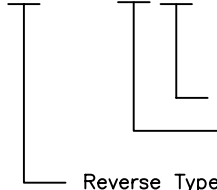
P.C.B Layout



NOTES:

- MATERIALS**
INSULATOR: HIGH TEMPERATURE THERMOPLASTIC UL94V-0
CONTACT: COPPER ALLOY UNDER PLATING-NICKEL OVERALL.
GOLD PLATED ON CONTACT & SOLDER TAIL AREA-TIN/LEAD.
GROUND MOUNT EAR: COPPER ALLOY-Tin/Lead OVER NI.
- MECHANICAL**
RETENTION FORCE: 0.98 N MIN.
- ELECTRICAL**
VOLTAGE RATING: 100V AC.
INSULATION RESISTANCE: 1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC.
CONTACT RESISTANCE: 40 MILLIOHMS MAX.
CURRENT RATING: 0.5 A.
- ENVIRONMENT**
OPERATION TEMPERATURE: -55°C ~ +85°C.
- UNSPECIFIED TOLERANCE:** .XX ±0.25[0.010]
.X ±0.30[0.012]

XSDC-3-09M4-K000-10



- Color : K -- Black
Contact Area Plating
2--3u" Gold Plated
3--5u" Gold Plated
4--10u" Gold Plated
5--15u" Gold Plated

Reverse Type

<h1>X MULTIPLE</h1>		CONNECTING THE INFORMATION AGE
XMULTIPLE ASIA 3F, No. 60, Juiuen St., Taipei, 104, Taiwan, R.O.C.		XMULTIPLE USA 543 Country Club Drive #B 128 Simi Valley, CA 93065
THIS DRAWING IS A CONTROLLED DOCUMENT.		CUSTOMER/NO: XSDC-3-09M4-K000-10
TITLE: SECURE DIGITAL MEMORY CARD CONNECTOR NORMAL REVERSE TYPE		DWG NO: XSDC-3-09M4-K000-10
PART NO: XSDC-3-09M4-K000-10		DRAWN: JEFF
		CHKD: FUTIEN
DIMENSIONS mm[inch]		DATE: 12/03/04
SHEET 1 of 1		REV 01